

07-19-05

AF
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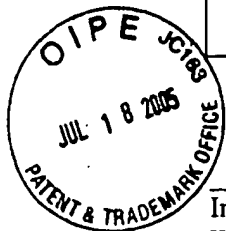
I hereby certify that this correspondence is being deposited with the U.S. Postal Service as Express Mail, Airbill No. EV703276511US, in an envelope addressed to: MS AF; Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on the date shown below.

Dated: July 18, 2005

Signature: *[Signature]*

(Grace A. Wise)

Docket No.: 03226/387001; P9280
(PATENT)



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Wen-Chun Zheng, et al.

Confirmation No.: 6609

Application No.: 10/824,455

Art Unit: 2811

Filed: April 14, 2004

Examiner: D. W. Owens

For: LIDLESS CHIP PACKAGE EFFECTIVELY
HAVING CO-PLANAR FRAME AND
SEMICONDUCTOR DIE SURFACES

REPLY UNDER 37 C.F.R. § 1.116

MS AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Okay to enter
DWO 7/29/05

Dear Sir:

In response to the final Office Action dated June 2, 2005, please reconsider the present application in view of the following.

07/20/2005 TBESHAH1 00000015 10824455

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